



***FOR IMMEDIATE RELEASE***

**High Density Package Users Group and IPC Sign MoU,  
Strengthening Collaboration and Value to Membership**

**Cave Creek, AZ, USA, June 24, 2020** – IPC and High Density Package Users Group (HDP), a trade organization representing companies involved in the supply chain of manufacturing products that utilize high-density electronic packages and printed circuit boards, have signed a Memorandum of Understanding (MoU), enabling a strengthened partnership, increased technical collaboration between groups, and providing a mutual path toward emerging and disruptive high density interconnect (HDI) technologies.

“Both IPC and HDP are member-driven organizations,” said Matt Kelly, IPC chief technologist. “Working together, both organizations will focus on next generation HDI technology projects to benefit the electronics manufacturing industry. HDP is very well established with more than 25 years of experience in R&D technology development. Resultant, new HDI learning and solutions will help drive IPC standards development activities as well as training and education programs.”

IPC and HDP have successfully worked together for many years on such electronics industry issues as electrochemical migration, high density ball grid arrays, board thickness on solder joint reliability and members of HDP have presented papers at IPC APEX EXPO on high frequency loss test methods for laminate materials and smooth copper signal integrity.

“A closer working relationship between IPC and HDP will bring significant advantages to both organizations, and as a result, to the industry,” noted Marshall Andrews, executive director of HDP. “Electronics manufacturing technology is moving



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faster than ever with the introduction of 5G and automotive applications. Close cooperation at all levels of the supply chain will be necessary to address issues and implement the new materials and processes required to keep moving forward. IPC and HDP will help make those changes smooth and reliable.”

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### **About IPC**

IPC ([www.IPC.org](http://www.IPC.org)) is a global industry association based in Bannockburn, Ill., dedicated to the competitive excellence and financial success of its 5,900 member-company sites which represent all facets of the electronics industry, including design, printed board manufacturing, electronics assembly and test. As a member-driven organization and leading source for industry standards, training, market research and public policy advocacy, IPC supports programs to meet the needs of an estimated \$2 trillion global electronics industry. IPC maintains additional offices Washington, D.C.; Atlanta, Ga.; Miami, Fla.; Brussels, Belgium; Bangalore and New Delhi, India; Bangkok, Thailand; and Qingdao, Shanghai, Shenzhen, Chengdu, Suzhou and Beijing, China.

### **About HDP User Group**

HDP User Group ([www.hdpug.org](http://www.hdpug.org)) is a global research and development organization based in Cave Creek Arizona, is dedicated to “reducing the costs and risks for the Electronics Manufacturing industry when using advanced electronic packaging and assembly.” This international industry led group organizes and conducts R&D programs to address the technical issues facing the industry, including design, printed circuit board manufacturing, electronics assembly, and environmental compliance. HDP User Group maintains additional offices in Austin, Texas, and Singapore.

For more information, visit HDP User Group on the Internet at [www.hdpug.org](http://www.hdpug.org) or contact Darryl Reiner at [darrylr@hdpug.org](mailto:darrylr@hdpug.org), phone number +1 480-951-1963